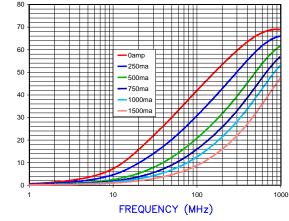
# MI0805K400R-10

# PHYSICAL DIMENSIONS:

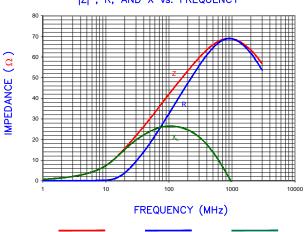
D 0.51 [.020] ± 0.25 [.010]

# Z vs FREQUENCY IMPEDANCE UNDER DC BIAS

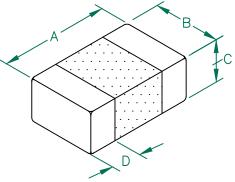


**IMPEDANCE** 





AGILENT E4991A RF Impedance/Material Analyzer HP 16194A Test Fixture. TEST REF. 3227

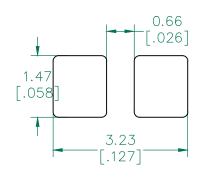


ELECT	RICAL CHARACTERISTICS:						
Z @ 100MHz ( Ω )		DCR (Ω)	Rated Current				
Nominal	40						
Minimum	30						
Maximum	50	0.050	1500 mA				

### NOTES: UNLESS OTHERWISE SPECIFIED

- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 4000 PCS/REEL, PAPER TAPE.
- 2. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 3. TERMINATION FINISH IS 100% TIN.
- 4. OPERATING TEMP. RANGE: -40°C~+125°C. (INCLUDING SELF-HEATING)

#### LAND PATTERNS FOR REFLOW SOLDERING



# (For wave soldering, add 0.763 [.030] to this dimension.)

# 

DIMENSIONS ARE IN mm [INCHES].			This print is the property of Laird							
				Tech, and is loaned in confidence subject to return upon request	d		- 4	1,		
				with the understanding that no			Laird			
$ldsymbol{ldsymbol{ldsymbol{eta}}}$				copies shall be made without th written consent of Laird Tech. A						
				rights to design or invention are	_					
				reserved.						
l D	ADD OPERATING TEMPERATURE	08/05/13	QU	PROJECT/PART NUMBER:		REV	PART T	YPE:	DRAWN BY:	
	UPDATE LAIRD LOGO AND REFLOW CURVE			MI0805K400R-10		D	CO-FIRE		JRK	
С	CHANGE TO PAPER TAPE	03/04/10	ÿ			_	-		•	
В		08/06/08			SCA	NIS		SHEET:	SHEET:	
Α	ORIGINAL DRAFT	03/11/04	JRK	CAD #	TOC			4 . 6 4		
RE\		DATE	INT					1 of 1		

## RECOMMENDED SOLDERING CONDITIONS